Product Change Notification

Change Notification #:	**115990 - 00**
Change Title:	**Select SKUs for Intel® Optane™ SSD 900P Series PCN 115990-00, Label, Label Updates**
Date of Publication:	**December 12, 2017**

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

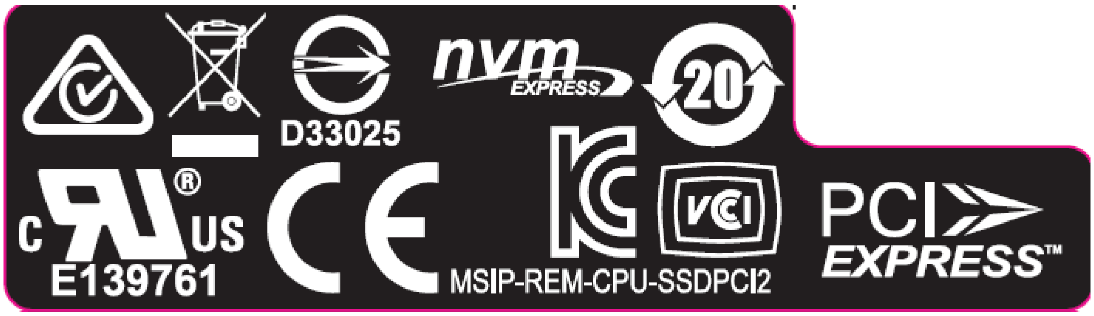
Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 27, 2017

Description of Change to the Customer:

The Intel® Optane™ SSD 900P Series SKUs listed in the Products Affected Table below will have the following changes.

1. The regulatory label will be updated to include additional logos. See pictures below.

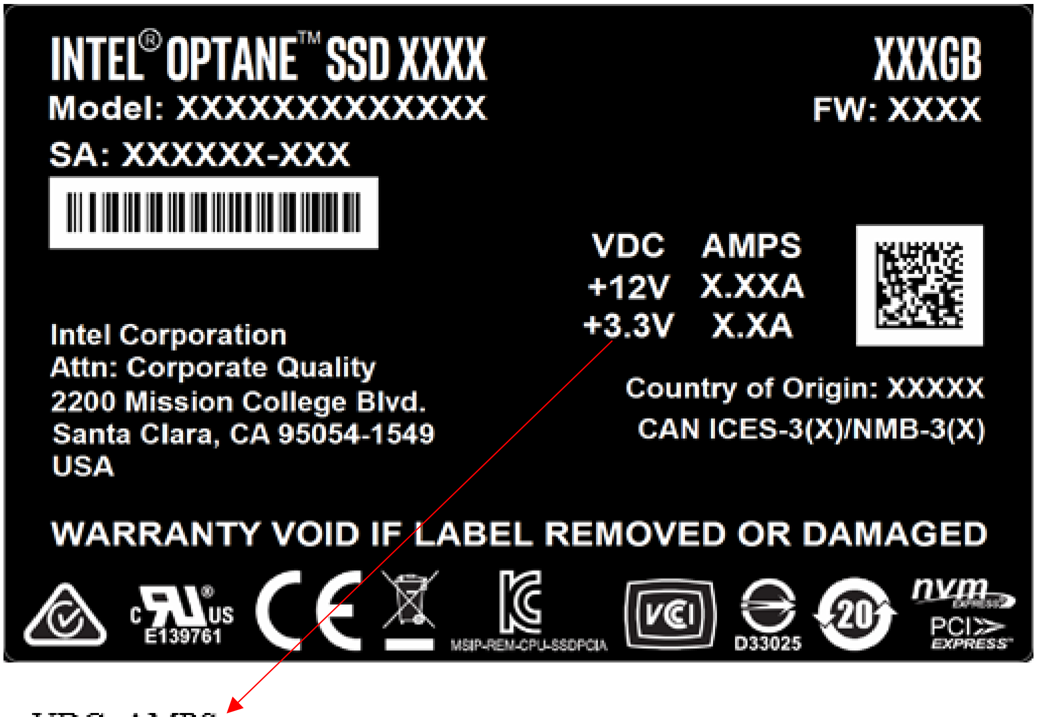
Before



After

2. The AIC HVM label will have logo changes and voltage and current changes. See pictures and table below.

Before



INTEL® OPTANE™ SSD XXXX
Model: XXXXXXXXXXXXX
SA: XXXXXX-XXX

XXXGB
FW: XXXX

VDC	AMPS
+12V	X.XXA
+3.3V	X.XA

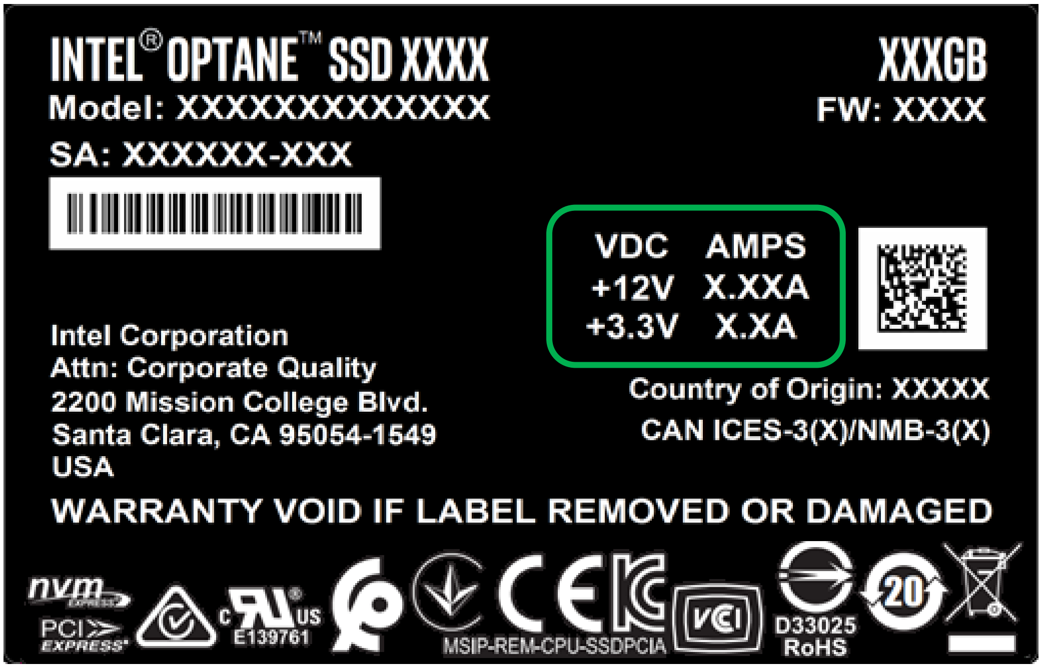
Intel Corporation
Attn: Corporate Quality
2200 Mission College Blvd.
Santa Clara, CA 95054-1549
USA

Country of Origin: XXXXX
CAN ICES-3(X)/NMB-3(X)

WARRANTY VOID IF LABEL REMOVED OR DAMAGED

VDC	AMPS
+12V	1.63A
+3.3V	0.3A

After



INTEL® OPTANE™ SSD XXXX
Model: XXXXXXXXXXXXX
SA: XXXXXX-XXX

XXXGB
FW: XXXX

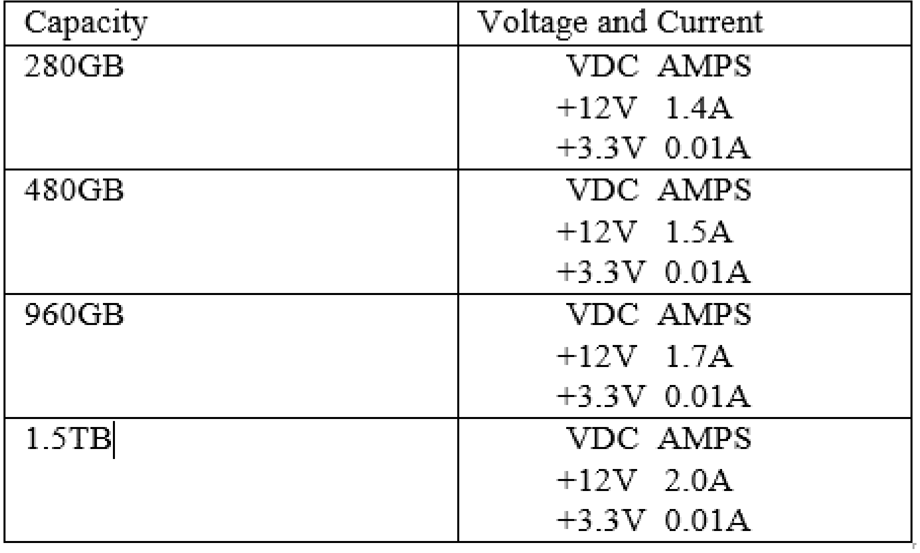
VDC	AMPS
+12V	X.XXA
+3.3V	X.XA

Intel Corporation
Attn: Corporate Quality
2200 Mission College Blvd.
Santa Clara, CA 95054-1549
USA

Country of Origin: XXXXX
CAN ICES-3(X)/NMB-3(X)

WARRANTY VOID IF LABEL REMOVED OR DAMAGED

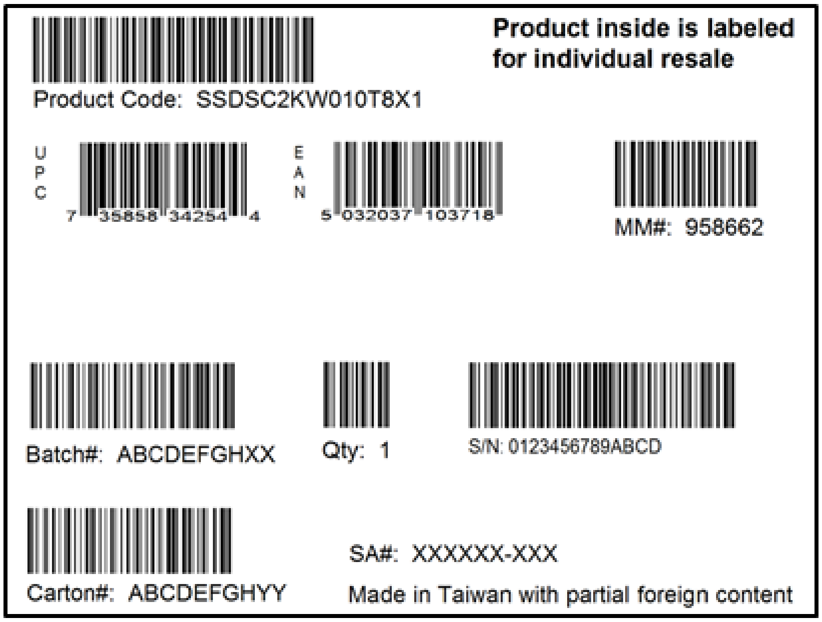
New values for voltage and current per capacity.



Capacity	Voltage and Current
280GB	VDC AMPS +12V 1.4A +3.3V 0.01A
480GB	VDC AMPS +12V 1.5A +3.3V 0.01A
960GB	VDC AMPS +12V 1.7A +3.3V 0.01A
1.5TB	VDC AMPS +12V 2.0A +3.3V 0.01A

3. The box label will be updated to include the Firmware version. See pictures below.

Before



Product inside is labeled for individual resale

Product Code: SSDSC2KW010T8X1

UPC 7 35858 34254 4

EAN 5 032037 103718

MM#: 958662

Batch#: ABCDEFGHXX

Qty: 1

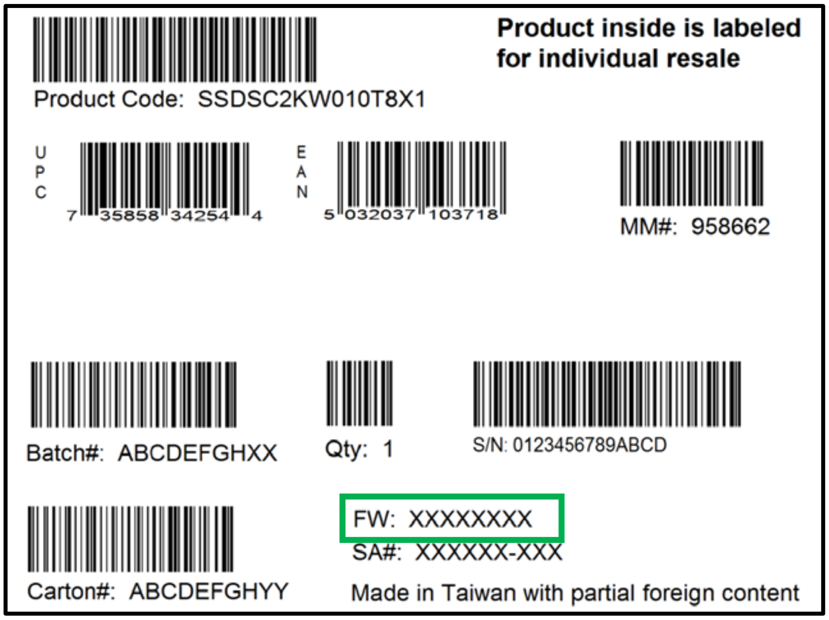
S/N: 0123456789ABCD

Carton#: ABCDEFGHYY

SA#: XXXXXX-XXX

Made in Taiwan with partial foreign content

After



Product inside is labeled for individual resale

Product Code: SSDSC2KW010T8X1

UPC 7 35858 34254 4

EAN 5 032037 103718

MM#: 958662

Batch#: ABCDEFGHXX

Qty: 1

S/N: 0123456789ABCD

Carton#: ABCDEFGHYY

FW: XXXXXXXX

SA#: XXXXXX-XXX

Made in Taiwan with partial foreign content

Customer Impact of Change and Recommended Action:

There is no change to the Form, Fit, or Function of the product. The change is only to the labels.

Customers should be aware of the changes to the labels and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Name	**Product Code**	**MM#**	**Pre Change TA**	**Pre Change SA**
Intel® Optane™ SSD 900P Series (280GB, 1/2 Height PCIe x4, 3D Xpoint) Reseller Single Pack	SSDPED1D280GAX1	945760	H93319-303	H93321-303
Intel® Optane™ SSD 900P Series (480GB, 1/2 Height PCIe x4, 3D Xpoint) Reseller Single Pack	SSDPED1D480GAX1	945761	H93320-303	H93324-303
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint) Reseller Single Pack	SSDPE21D280GAX1	956949	J60242-101	J60248-101
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint)	SSDPE21D280GAM3	959525	J65427-101	J60248-101
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint)	SSDPE21D280GASM	962750	J78487-101	J60248-101
Intel® Optane™ SSD 900P Series (280GB, 2.5in PCIe x4, 3D XPoint)	SSDPE21D280GASX	962751	J78488-101	J60248-101
Intel® Optane™ SSD 900P Series (280GB, ½ Height PCIe 3.0 X4, 20nm 3D XPoint)	SSDPED1D280GASX	962752	J78489-303	H93321-303
Intel® Optane™ SSD 900P Series (480GB, ½ Height PCIe 3.0 X4, 20nm 3D XPoint)	SSDPED1D480GASX	962754	J78490-303	H93324-303

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
December 12, 2017	00	Originally Published PCN

Product Change Notification
115990 - 00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2017. Other names and brands may be claimed as the property of others.

3D XPoint, Axxia, Basis, Basis Peak, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, Curie, Flexpipe, Intel, the Intel logo, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Inside, the Intel Inside logo, Intel Insider, Intel Joule, Intel RealSense, Intel SingleDriver, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Iris, Itanium, MCS, MMX, Optane, Ostro, Pali, Pentium, picoArray, Picochip, picoXcell, Puma, Quark, SMARTi, Soletta, Sound Mark, StarPro, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, True Key, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos. Learn how to use Intel Trademarks and Brands correctly at http://www.intel.com/intel/legal/tmusage2.htm.